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In the Claims:

1. (Original) An electronic device (1)
 - 2. - with a base plate (2),
 - 3. - with an electronics housing (3) which is connected to the base plate (2), with at least one bond contact bearer (5),
 - 4. characterised in that the bond contact bearer (5) is supported on the base plate (2) by a supporting body (6) in such a manner that the supporting body (6) exerts a pretension force onto the bond contact bearer (5).
1. 2. (Original) An electronic device according to claim 1, characterised in that a projection of the supporting body (6) above the base plate (2) is greater than the distance between the bond contact bearer (5) and the base plate (2).

Claims 3 and 4 (Canceled).

1. 5. (Currently amended) A procedure for bonding [[an]] the electronic device (1) with the following procedural stages:
according to claim 1, comprising the steps:
 - 4. provision of a
 - 5. providing the base plate (2),
 - 6. connection of an
 - 7. connecting the electronics housing (3) via [[a]] the supporting body (6) with the base plate (2) in such a

9 manner that the supporting body (6) exerts [[a]] the
10 pretension force onto the bond contact bearer (5), and
11 ~~creation of~~

12 creating a bond connection between the bond contact
13 bearer (5) of the electronics housing (3) and an additional
14 bond contact bearer.

1 6. (Previously presented) An electronic device according to
2 claim 1, characterized in that the supporting body (6)
3 represents a separate component from the base plate (2),
4 which is mechanically connected to the electronics housing
5 (3).

1 7. (Previously presented) An electronic device according to
2 claim 1, characterized in that the supporting body (6) is
3 designed as a projecting ring or as a plurality of
4 projecting individual segments.

[RESPONSE CONTINUES ON NEXT PAGE]